Lam Research Corporation Introduces ExelanTM Next-Generation Dual-Frequency Dielectric Etch System

Lam Research Corporation Introduces Exelan^{TM} Next-Generation Dual-Frequency Dielectric Etch System FREMONT, Calif., June 1, 1999 - Lam Research Corporation (Nasdaq: LRCX), a leading supplier of wafer fabrication equipment to the worldwide semiconductor industry, today introduced its Exelan next-generation dual-frequency dielectric etch system. Exelan is designed specifically to provide advanced processing capability while delivering the industry's lowest cost of ownership (CoO) per wafer, as much as 50 percent below competitive products.

Exelan's extensive process portfolio includes all dual damascene structures as well as contacts, vias, spacers, and passivation etch in doped and undoped oxides and low k dielectrics.

The Exelan system's streamlined, innovative design allows ease of serviceability and high reliability. The system also includes sophisticated closed-loop wafer area pressure control. Reliability and availability are driven to new industry highs while scheduled service and costs are the best among comparable tools.

"We are committed to increasing our customers' competitiveness by providing them with high productivity, high reliability systems at the lowest cost of ownership," stated Dr. Greg Campbell, vice president and general manager of the Etch Products Organization. "Lam's ability to meet that commitment is evidenced by the overwhelming customer acceptance of Exelan."

This press release contains certain forward-looking statements which are subject to the Safe Harbor provisions created by the Private Securities Litigation Reform Act of 1995. Such forward-looking statements relate to anticipated performance, capabilities, applications, and competitiveness of the company's products and market transition to new processes. Such statements are based on current expectations and are subject to risks, uncertainties, and changes in condition, such as may arise from introduction of such products into production, and other risks detailed in documents filed with the Securities and Exchange Commission, including specifically the report on Form 10-K for the year ended June 30, 1998, and the Form 10-Q for the quarter ended March 31, 1999. The company undertakes no obligation to update the information in this Press Release.

Lam Research Corporation is a leading supplier of wafer fabrication equipment and services to the world's semiconductor industry. The company's common stock trades on the Nasdaq National Securities Market under the symbol "LRCX". Lam's World Wide Web address is http://www.lamrc.com.

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